ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,

200 V, 4 A Schottky Fast Soft-Recovery Power Rectifier

SMC Power Surface Mount Package

Features

- Lower Forward Voltage than any Ultrafast Rectifier: $V_F < 0.61 \ V$ at $150 ^{\circ} \mathrm{C}$
- Fast Switching Speed: Reverse Recovery Time $(t_{RR}) < 35$ ns
- Soft Recovery Characteristics: Softness Factor $(t_b/t_a) \ge 1$
- Highly Stable Over Temperature
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Benefits

- Significantly Reduced EMI
- Eliminates the Need of Snubber Circuits
- Low Switching and Heat Losses
- Improved Thermal Management

Applications

- Engine and Convenience Control Systems
- Motor Controls
- Battery Chargers and Switching Power Supplies

Mechanical Characteristics

- Small Compact Surface Mount Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- ESD Ratings:
 - ◆ Machine Model = A
 - ♦ Human Body Model = 1C
- Cathode Polarity Band



ON Semiconductor®

www.onsemi.com

SCHOTTKY RECTIFIER 4 AMPS, 200 VOLTS



SMC 2-LEAD CASE 403AC



MARKING DIAGRAM



B421 = Specific Device Code A = Assembly Location*

= Year

WW = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)

*The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]	
MBRS4201PT3G	SMC 2-Lead (Pb-Free)	2,500 / Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (Rated V_R , $T_L = 70^{\circ}C$)	I _{F(AV)}	4	А
Nonrepetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	А
Operating Junction Temperature	TJ	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead	$R_{ heta JL}$	11	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage ($I_F = 4 \text{ A}, T_J = 25^{\circ}\text{C}$) ($I_F = 4 \text{ A}, T_J = 150^{\circ}\text{C}$)	V _F	0.86 0.62	V
Maximum Instantaneous Reverse Current (Rated V_R) (Rated DC Voltage, T_J = 25°C) (Rated DC Voltage, T_J = 150°C)	I _R	1.0 5.0	mA mA
Maximum Reverse Recovery Time (I _F = 1.0 A, di/dt = 100 A/ μ s, V _R = 30 V)	t _{rr}	35	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

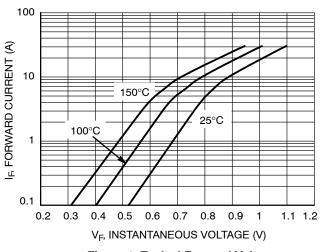
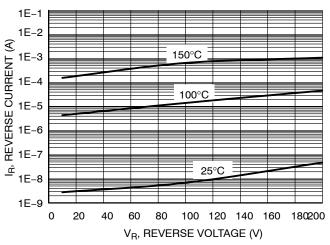


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



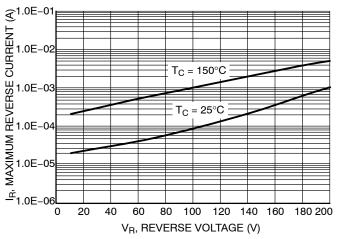


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

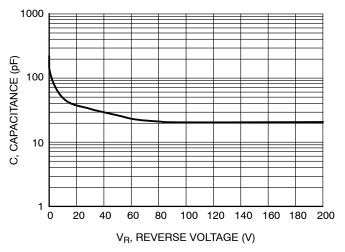


Figure 5. Typical Capacitance

TYPICAL CHARACTERISTICS

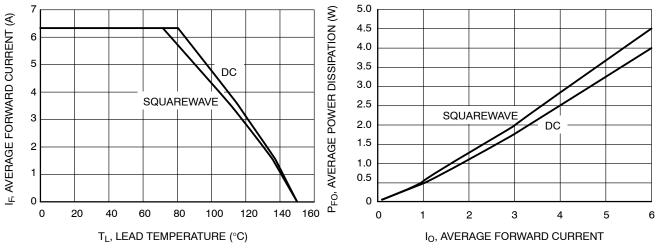


Figure 6. Derating Curve

Figure 7. Power Dissipation

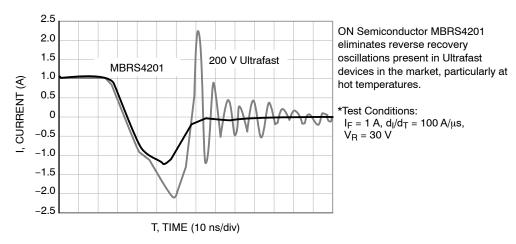
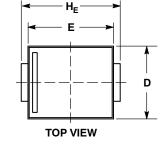
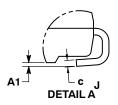


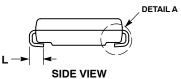
Figure 8. Reverse Recovery Time* (t_{RR}) at 125°C

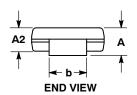
PACKAGE DIMENSIONS

SMC 2-LEAD CASE 403AC **ISSUE B**







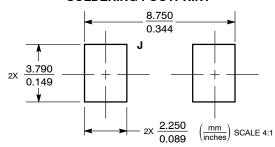


NOTES:

- DIMENSIONING AND TOLERANCING PER ANME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.254mm PER SIDE. DIMENSIONS D AND E TO BE DETERMINED AT DATUM H. DIMENSION b SHALL BE MEASURED WITHIN THE AREA
- DETERMINED BY DIMENSION L.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.95	2.61	0.077	0.103
A1	0.05	0.20	0.002	0.008
A2	1.90	2.41	0.075	0.095
b	2.90	3.20	0.114	0.126
С	0.15	0.41	0.006	0.016
D	5.55	6.25	0.219	0.246
E	6.60	7.15	0.260	0.281
HE	7.75	8.15	0.305	0.321
L	0.75	1.60	0.030	0.063

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor, "Typical" parameters which may be provided in ON Semiconductor data sheet sand/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative